

Title (en)
CONTACTLESS INTERCONNECTION SYSTEM

Title (de)
KONTAKTLOSES VERBINDUNGSSYSTEM

Title (fr)
SYSTEME D'INTERCONNEXION SANS CONTACT

Publication
EP 1273040 A2 20030108 (EN)

Application
EP 01924985 A 20010412

Priority
• US 0112020 W 20010412
• US 54863600 A 20000413
• US 54894000 A 20000413

Abstract (en)
[origin: WO0180316A2] A contactless interconnecting system is provided between a computer chip package and a circuit board. The chip package has a substantially planar lower surface with a pattern of discrete terminal lands. The circuit board has a substantially planar upper surface spaced from and generally parallel to the lower surface of the chip package. A pattern of discrete circuit pads on the upper surface are aligned with the terminal lands. A plurality of discrete interposer members are disposed between the terminal lands and the circuit pads and are in a pattern corresponding to and aligned with the aligned patterns of the terminal lands and circuit pads. The interposer members are preferably of a material having a higher dielectric constant than that of the material filling the gaps between interposer members.

IPC 1-7
H01L 23/498; **H01L 23/64**

IPC 8 full level
H01L 23/12 (2006.01); **H01L 23/48** (2006.01); **H05K 1/18** (2006.01)

CPC (source: EP KR)
H01L 23/48 (2013.01 - EP); **H01L 23/498** (2013.01 - KR); **H01L 24/48** (2013.01 - EP); **H01L 2224/05599** (2013.01 - EP);
H01L 2224/48091 (2013.01 - EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/85399** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP);
H01L 2924/10253 (2013.01 - EP); **H01L 2924/19041** (2013.01 - EP)

Citation (search report)
See references of WO 0180316A2

Designated contracting state (EPC)
DE FR GB SE

DOCDB simple family (publication)
WO 0180316 A2 20011025; **WO 0180316 A3 20020321**; AU 5158801 A 20011030; CN 1237612 C 20060118; CN 1422440 A 20030604;
EP 1273040 A2 20030108; JP 2003531496 A 20031021; JP 3701242 B2 20050928; KR 20020090233 A 20021130; TW 547773 U 20030811

DOCDB simple family (application)
US 0112020 W 20010412; AU 5158801 A 20010412; CN 01807908 A 20010412; EP 01924985 A 20010412; JP 2001577610 A 20010412;
KR 20027013712 A 20021012; TW 90205708 U 20010412